

INFORMATION

Halide free

PRODUCT No. : Q13MC1462000200

MODEL : MC-146

32.768 kHz 12.5 pF $\pm$ 20

INFO. No. : Q09-283-22A

DATE : Mar. 10. 2010

EPSON TOYOCOM CORPORATION

8548 Naka-minowa
Minowa-machi Kamiina-gun
Nagano-ken
399-4696 Japan

INTRODUCTION

1. The contents is subject to change without notice.
Please exchange the specification sheets regarding
the product's warranty.
2. This sheet is not intended to guarantee or provide
an approval of implementation of industrial patents.
3. We have prepared this sheet as carefully as possible.
If you find it incomplete or unsatisfactory in any
respect, We would welcome your comments.

1) RoHS compliant

MC-146 contains lead in high melting type solder which is exempted in RoHS directive.

2) This Product supplied (and any technical information furnished, if any) by Epson Toyocom Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes.

Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.

3) This product listed here is designed as components or parts for electronics equipment in general consumer use.

We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an systems, and medical equipment, the functional purpose of which is to keep extra high reliability, such as satellite, rocket and other space life.

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[1] Absolute maximum ratings

No.	Item	Symbol	Rating value			Unit	Note
			Min.	Typ.	Max.		
1	Storage temperature range	T_stg	- 55		+ 125	°C	Suppose to be within CI STD at + 25 °C ± 3 °C.
2	Maximum level of drive	GL		1.0		μW	

[2] Operating range

No.	Item	Symbol	Rating value			Unit	Note
			Min.	Typ.	Max.		
1	Operating temperature range	T_use	- 40		+ 85	°C	
2	Level of drive	DL	0.01	0.1	0.5	μW	
3	Vibration mode		Fundamental				

[3] Static characteristics

No.	Item		Symbol	Value	Unit	Conditions
1	Nominal Frequency		f_nom	32.768	kHz	
2	Frequency tolerance		f_tol	± 20	× 10 ⁻⁶	CL = 12.5 pF Ta = + 25 ± 3 °C Level of drive : 0.1 μW Not include aging
3	Motional resistance		R1	65 Max.	kΩ	CI meter : Saunders 140B Level of drive : 0.5 μW
4	Motional capacitance		C1	1.9 Typ.	fF	
5	Shunt capacitance		C0	0.8 Typ.	pF	
6	Frequency temperature characteristics	Turnover temperature	Ti	+ 25 ± 5	°C	Values are calculated by The frequencies at + 10, + 25, + 40 °C with C-MOS circuit.
		Parabolic coefficient	B	- 0.04 Max.	× 10 ⁻⁶ /°C ²	
7	Isolation resistance		IR	500 Min.	MΩ	DC 100 V ± 15, 60 seconds Between terminal # 1 and terminal # 2
8	Frequency Aging		f_age	± 3	× 10 ⁻⁶ /year	Ta = + 25 °C ± 3 °C Level of drive : 0.1 μW

[4] Environmental and Mechanical characteristics

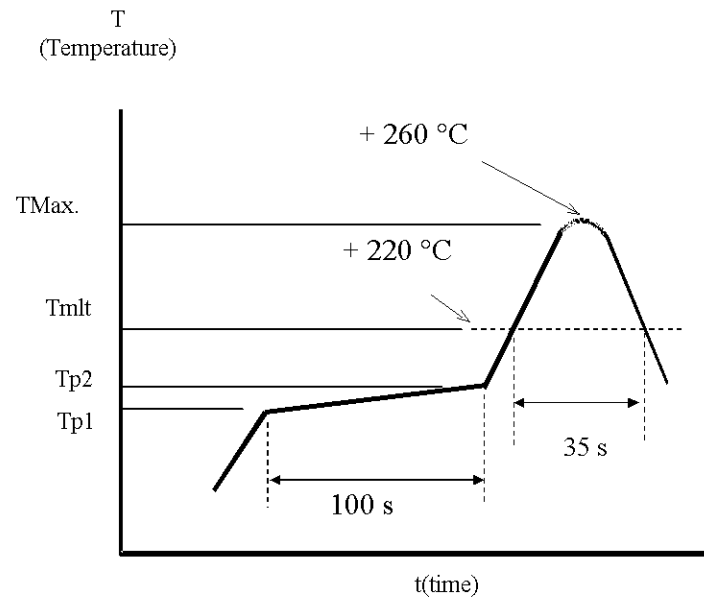
No.	Items	Value *1*2 $\Delta f/f [1 \times 10^{-6}]$	Conditions
1	Shock	*3 ± 5	100 g dummy (EPSON TOYOCOM Standard) drop from 1500 mm height on to the concrete 3 directions 10 times
2	Vibration	*3 ± 3	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s^2 10 Hz $\rightarrow$ 500 Hz $\rightarrow$ 10 Hz 15 min./cycle 6 h (2 hours , 3 directions)
3	Resistance to soldering heat (Reflow characteristics)	*3 ± 5	Treat the Reflow 2 times by the following profile in the next page
4	High temperature storage	*3 a) ± 20 b) ± 10	a) $+ 125^\circ\text{C} \times 1\,000 \text{ h}$ b) $+ 85^\circ\text{C} \times 1\,000 \text{ h}$
5	Low temperature storage	*3 ± 10	$- 55^\circ\text{C} \times 1\,000 \text{ h}$
6	Temperature humidity storage	*3 ± 10	$+ 85^\circ\text{C} \times 85\% \text{RH} \times 1000 \text{ h}$
7	Temperature cycle	*3 ± 10	$- 55^\circ\text{C} \leftrightarrow + 125^\circ\text{C}$ 30 minutes at each temperature 100 cycles
8	Shear	No peeling-off at a soldered part	10 N press the side for 10 s $\pm 1 \text{ s}$. Ref. IEC 60068-2-21
9	Pull-off	No peeling-off at a soldered part	10 N press the side for 10 s $\pm 1 \text{ s}$. Ref. IEC 60068-2-21
10	Substrate bending	No peeling-off at a soldered part	Bending width reaches 3mm and hold for 5 s $\pm 1 \text{ s} \times$ 1 time Ref. IEC 60068-2-21
11	Solderability	Termination must be 95 % covered with fresh solder	Dip termination into solder bath at $+ 235 \pm 5^\circ\text{C}$ for 3 s (Using rosin flux)
12	Solvent resistance	The marking shall be legible	Ref. JIS C 0052 or IEC 60068-2-45

- Note
- *1 Each test done independently.
 - *2 Measuring 1 h to 24 h later leaving in room temperature after each test.
 - *3 Pre conditionings
 - $+ 125^\circ\text{C} \times 24 \text{ h}$ to $+85^\circ\text{C} \times 85\% \text{RH} \times 48 \text{ h} \rightarrow$ reflow 2 times
 - Initial value shall be after 24 h at room temperature.
 - Shift series resistance at after above tests should be less than $\pm 15\%$ or less than $\pm 5 \text{ k}\Omega$
In case Resistance to soldering heat, high temperature storage ($\pm 125^\circ\text{C} \times 1\,000 \text{ h}$) shift series
resistance at after above tests should be less than $\pm 20\%$ or $\pm 10 \text{ k}\Omega$

◆ Air-reflow

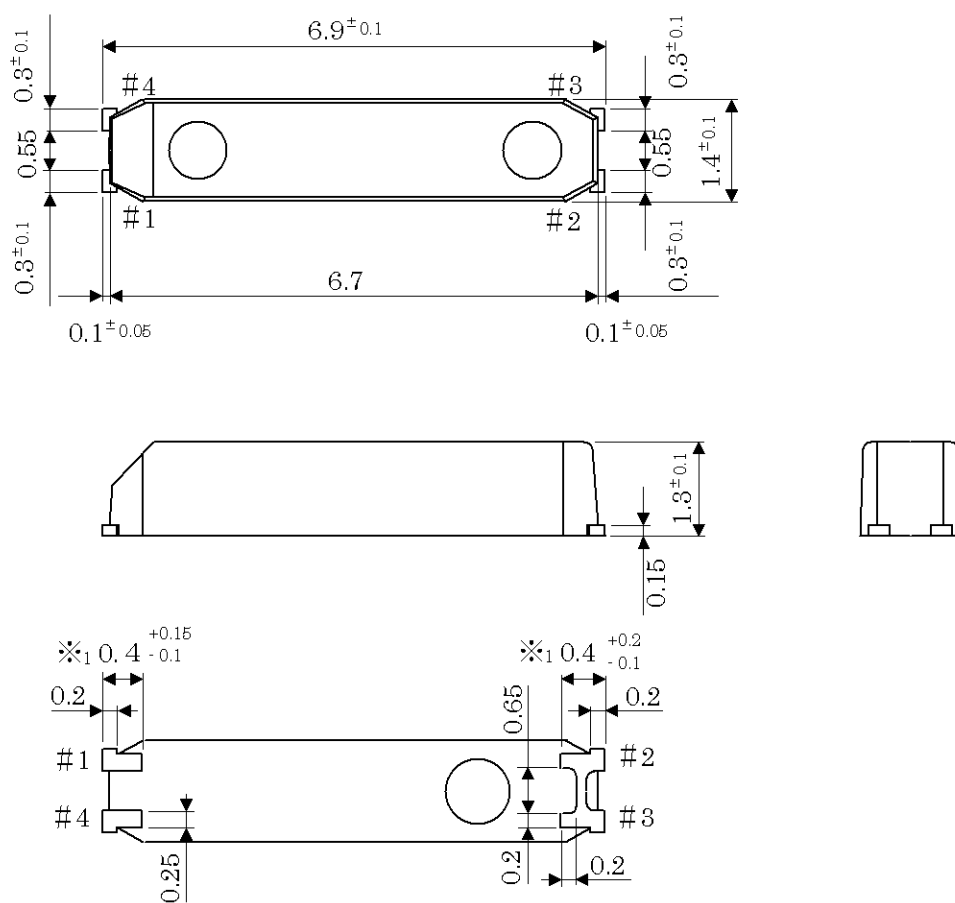
Pre heating temperature : $T_{p1} \sim T_{p2} = +170\text{ }^{\circ}\text{C}$

Peak temperature must not exceed $+260\text{ }^{\circ}\text{C}$ and the duration of over $+220\text{ }^{\circ}\text{C}$ should be 35 s



[5] Dimensions and Marking layout

1. Dimensions

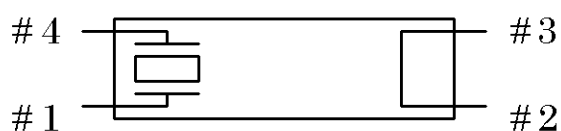


$\times_1$: Available area for soldering

$\times_2$: Metal may be exposed on the top or bottom of this product.

This will not affect any quality, reliability or electrical spec.

2. Internal Connection



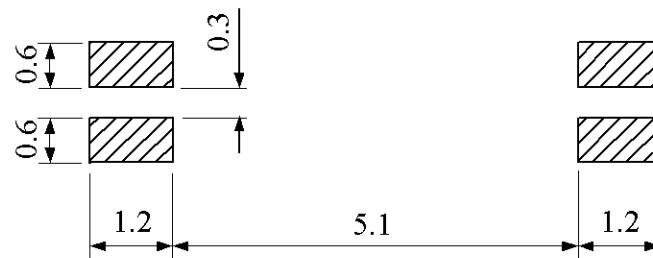
Terminal thickness	0.15 mm
Lead Frame	42Alloy
Terminal treatment	Sn plating $15 \pm 5 \mu\text{m}$
Molding	Epoxy Compound (Halide free)
Compound color	Black

Do not connect # 2 and # 3 terminals to any external circuits (including GND).

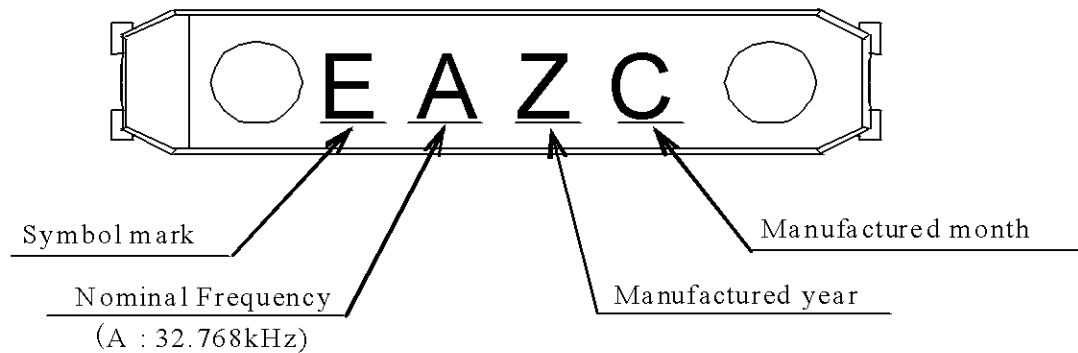
Type	MC-146	Unit	1 = 1 mm
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3. Recommended soldering pattern

Unit : 1 = 1 mm



4. Marking layout



Symbol of Manufacturing year

Year digit	1	2	3	4	5	6	7	8	9	0
Marking (Sn plating Terminal)	M	N	R	S	T	U	V	W	X	Z

Year digit(1st) of the Production

Symbol of Manufacturing month

Mounth digit	1	2	3	4	5	6	7	8	9	10	11	12
Marking (Halide free Epoxy Compound)	A	B	C	D	E	F	G	H	J	K	L	M

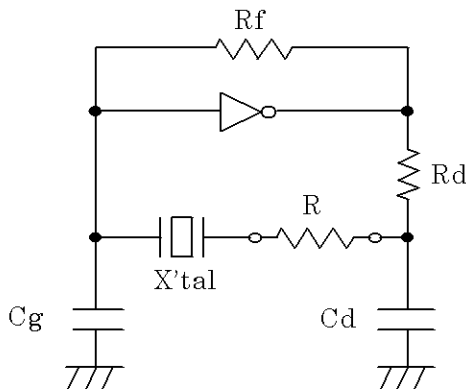
- ◆ The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.

Type	MC-146	Unit	1 = 1 mm
------	--------	------	----------

[6] Notes

1. Max two (2) times reflow is allowed. Once miss soldering is happened, hand work soldering by soldering iron is recommended. (+ 350 °C × within 5 sec.)
2. Patterning should be followed by our recommended one.
3. Applying excessive excitation force to the crystal unit may cause deterioration damage.
4. Unless adequate negative resistance is allocated in the oscillation circuit, start up time of oscillation may be increased, or no oscillation may occur.

How to check the negative resistance.



- (1) Connect the resistance (R) to the circuit in series with the crystal unit.
- (2) Adjust R so that oscillation can start (or stop).
- (3) Measure R when oscillation just start (or stop) in above (2).
- (4) Get the negative resistance
 $-R = R + CI$ value.
- (5) Recommended -R
 $|-R| > CI \times (5 \sim 10)$

5. The shortest patterning line on board is recommendable.
Too long line on board may cause of abnormal oscillation.
6. To avoid mull function, no pattern under or near the crystal is allowed.
Solder paste should be more than 150 μm thickness.
7. This device must be stored at the normal temperature and humidity conditions before mounting on a board.
8. Too much exciting shock or vibration may cause deterioration on damage.
Depending on the condition such as a shock in assembly machinery, the products may be damaged.
Please check your condition in advance to maintain shock level to be smallest.
9. Depending on the conditions, ultrasonic cleaning may cause resonant damage of the internal crystal unit. Since we are unable to determine the conditions (type of cleaning unit, power, time, conditions inside the bath, etc.) to be used in your company, we cannot guarantee the safety of this unit when it is cleaned in an ultrasonic cleaner.
10. Ink marking may be damaged by some kind of solvent, please take precautions when choosing solvent by your selves.
11. Please refer to packing specification regarding how to storage the products in the pack.

TAPING SPECIFICATION

1. APPLICATION

This document is applicable to MC-146.

2. CONTENTS

Item No.	Item	Page
[1]	Taping specification	1 to 2
[2]	Inner carton	3
[3]	Shipping carton	
[4]	Marking	4
[5]	Quantity	
[6]	Storage environment	
[7]	Handling	

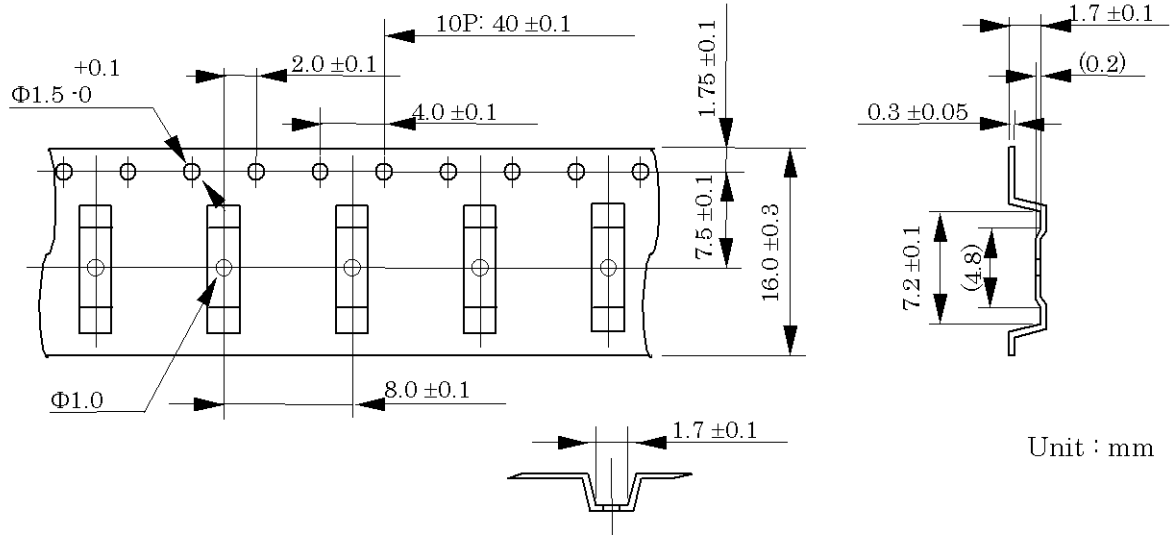
[1] Taping specification

Subject to EIA-481 , EIAJ EDX7602 , IEC 60286 , and JIS C0806.

(1) Tape dimensions TE1604L

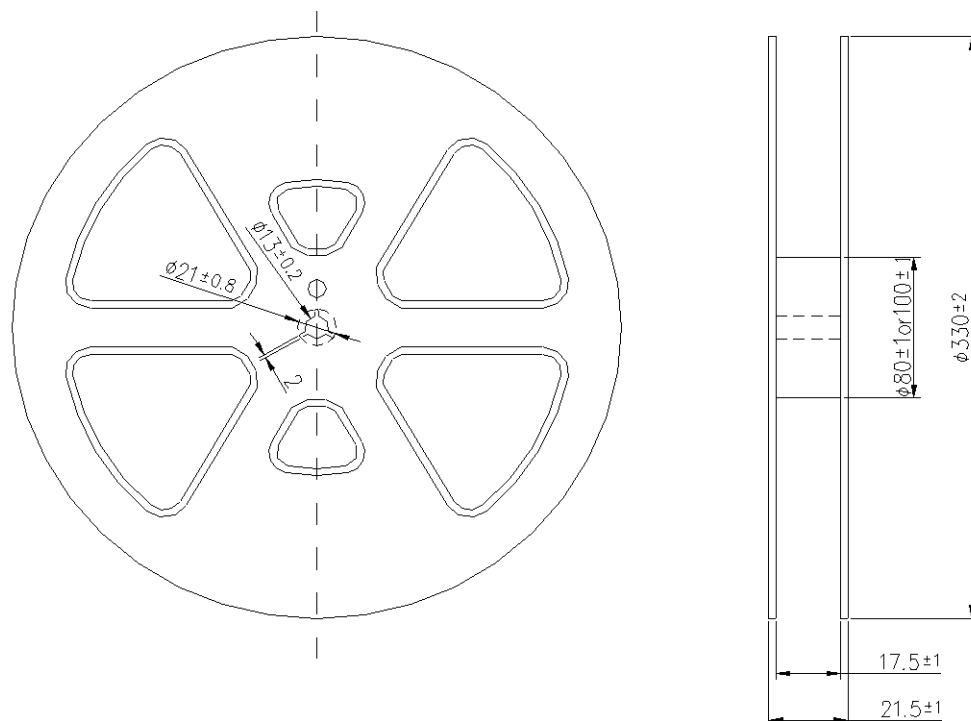
Material of the Carrier Tape : PS

Material of the Top Tape : PET+PE



(2) Reel dimensions

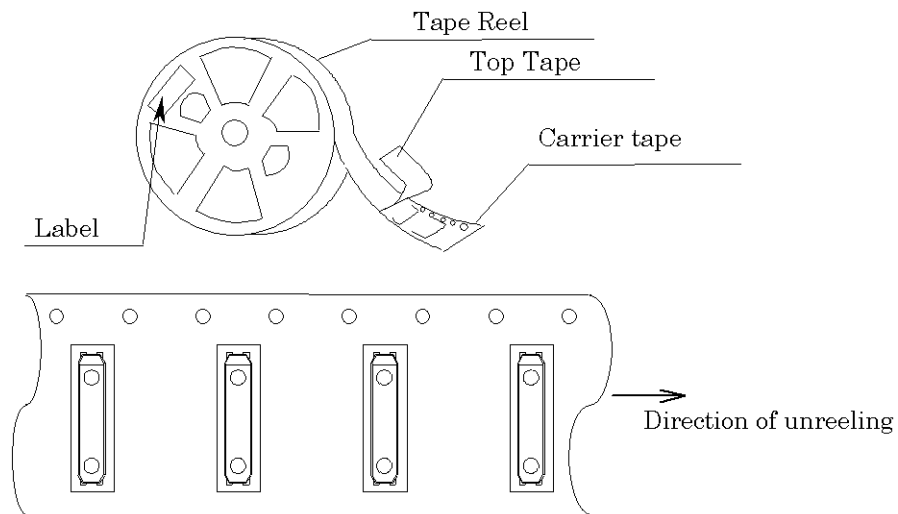
Material of the Reel : PS



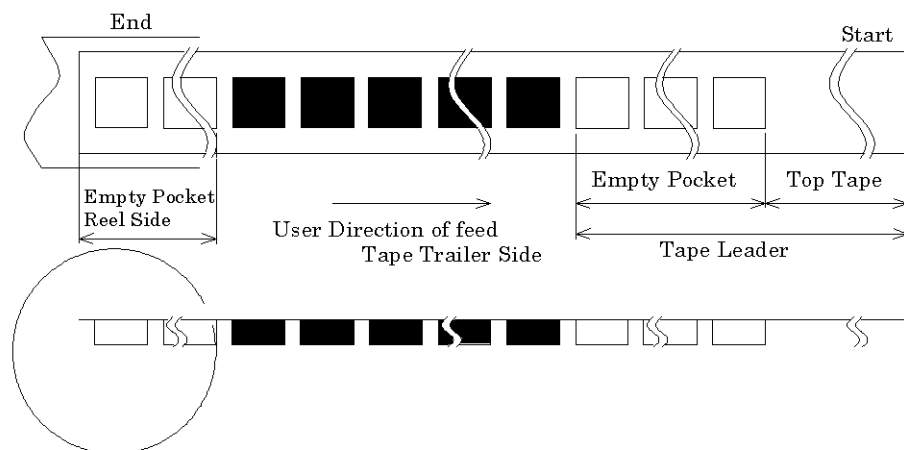
Form and Size of reel window shows are one of the example

(3) Packing

(a) Tape & Reel



(b) Start & End Point



(c) Peel force of the cover tape

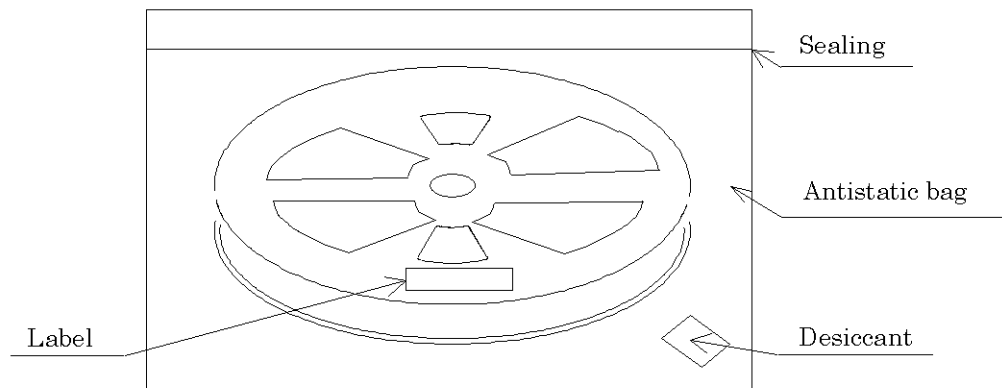
(1) angle : cover tape during peel off and the direction of unreeling shall be 165° to 180°.

(2) peel speed : 5 mm/s.

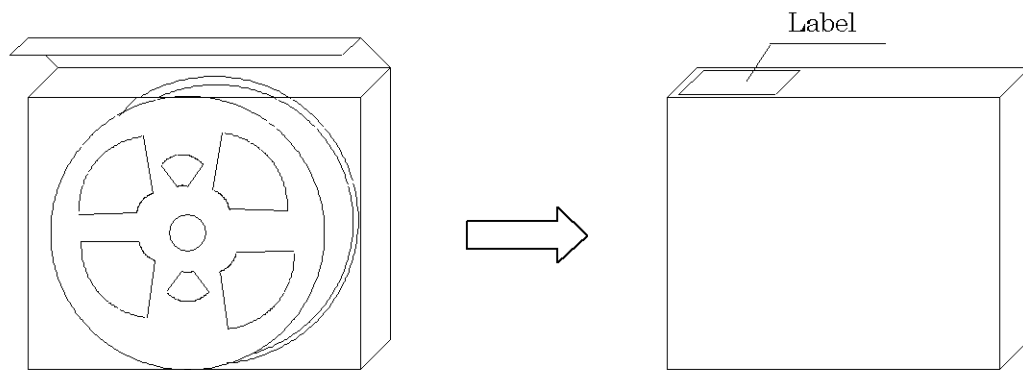
Item		Empty Space
Tape Leader	Top Tape	Min. 1 000 mm
	Carrier Tape	Min. 40 pockets
Tape Trailer	Top Tape	Min. 0 mm
	Carrier Tape	Min. 40 pockets

[2] Inner Carton

a) Packing to antistatic bag

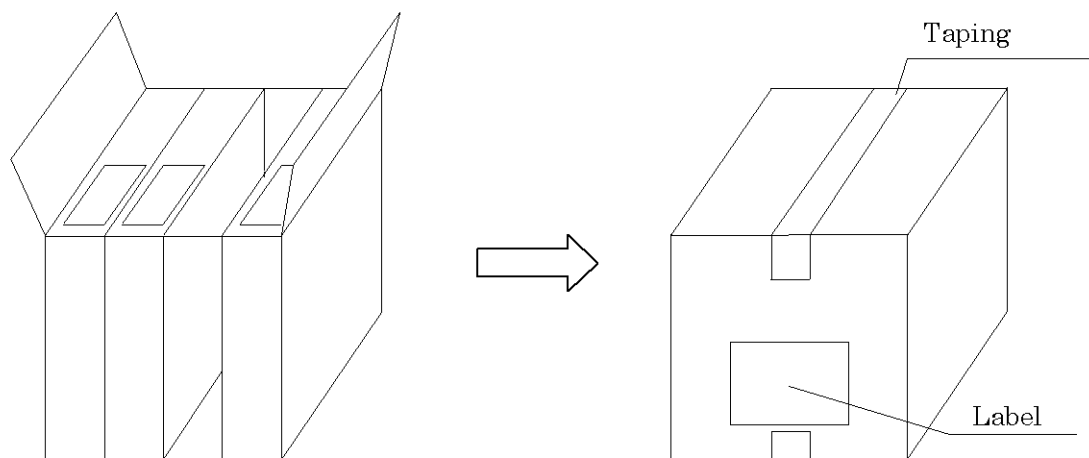


b) Packing to innercarton



[3] Shipping Carton

- Put inner boxes into an outer box.
- If there are room in the outer box, material is put in a shock absorbing together.



[4] Marking

- (1) Reel marking
 - Reel marking shall consist of :
 - 1) Parts name
 - 2) Quantity
 - 3) Manufacturing Date or symbol
 - 4) Manufacturer's Date or symbol
 - 5) Others (if necessary)
- (2) Inner carton marking
 - Same as Reel marking.
- (3) Shipping carton marking
 - Shipping carton marking shall consist of :
 - 1) Parts name
 - 2) Quantity

[5] Quantity

- 3 000 pcs./reel

[6] Storage environment

- (1) To storage the reel at +15 °C to +35 °C, 25 %RH to 85 %RH of Humidity.
- (2) To open the packing just before using.
- (3) Not to expose the sun.
- (4) Not to storage with some erosive chemicals.
- (5) Nothing is allowed to put on the reel or carton to prevent mechanical damage.

[7] Handling

To handle with care to prevent the damage of tape, reel and products.

- PROCESS QUALITY CONTROL -

CODE : MC-146

Control No : M-9803-AGE-2

SURFACE MOUNTING TYPE CRYSTAL

MC-146

10-Sep-08

EPSON TOYOCOM CORP.

INA PLANT QZ BU

PREPARED	CHECKED	APPROVED

MANUFACTURING PROCESS CHART	No	RESPONSIBLE SECTION	STANDARD AND SPECIFICATIONS	INSPECTION AND CONTROL ITEMS	INSPECTION METHOD	MEASURING INSTRUMENTS	DATA COLLECTION
LEAD FRAME CRYSTAL (SiO2 COATING) 1' INCOMING INSPECTION 2 CRYSTAL WELDING 3 TRANSFER MOULDING 4 1st PRESSING 5 SOLDER PLATING 6 MARKING 7 2nd PRESS 8 FINAL INSPECTION AND TAPING 9 OUTGOING INSPECTION 10-1 Pre-PACKING 10-2 PACKING EXPORT	1'	MALAYSIA PLANT (Sub-Contractor)	PURCHASING SPECIFICATION	APPEARANCE	SAMPLING	MICROSCOPE	IN-COMING INSPECTION
	2	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
			MANUFACTURING INSTRUCTION SHEET	DIMENSION	SAMPLING	T.M.S	PROCESS DATA SHEET
	3	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
	4	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
	5	MALAYSIA PLANT (Sub-Contractor)	SOLDER PLATING SPECIFICATION SHEET	S.P THICKNESS	SAMPLING	FLUOROSCOPY	PROCESS DATA SHEET
				APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
	6	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
	7	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
				DIMENSION	SAMPLING	VERTICAL COMPARATOR	PROCESS DATA SHEET
	8	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	ELECTRICAL CHARACTERISTIC	100% INSPECTION	T0 CHECKING By m/c	PROCESS DATA SHEET
			MANUFACTURING INSTRUCTION SHEET	TAPING STRENGTH	SAMPLING	PEEL BACK TESTER	PROCESS DATA SHEET
			QUALITY STD.	ELECTRICAL CHARACTERISTIC	SAMPLING	T0&C1 CHECKER	OGI INSP.SHEET
	9	MALAYSIA PLANT (Sub-Contractor)	QUALITY STD.	APPEARANCE	SAMPLING	MICROSCOPE	OGI INSP.SHEET
	10-1	MALAYSIA PLANT (Sub-Contractor)	MANUFACTURING INSTRUCTION SHEET	EXPORT CUSTOMER LIST	---	---	EXPORT DOCUMENTS
			DAILY SHIPPING LIST	FREQUENCY			
				QUANTITY			
	10-2	MALAYSIA PIANT	MANUFACTURING INSTRUCTION SHEET	EXPORT CUSTOMER LIST	---	---	EXPORT DOCUMENTS
			DAILY SHIPPING LIST	FREQUENCY			
				QUANTITY			

- PROCESS QUALITY CONTROL -

CODE : MC-146

Control No : M-9803-ANE-2

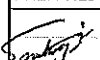
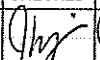
SURFACE MOUNTING TYPE CRYSTAL

MC-146

10-Sep-08

EPSON TOYOCOM CORP.

INA PLANT QZ BU

PREPARED	CHECKED	APPROVED
		

MANUFACTURING PROCESS CHART	No	RESPONSIBLE SECTION	STANDARD AND SPECIFICATIONS	INSPECTION AND CONTROL ITEMS	INSPECTION METHOD	MEASURING INSTRUMENTS	DATA COLLECTION
CRYSTAL (SiO2 COATING)	1'	SUB-CONTRACTOR	PURCHASING SPECIFICATION	APPEARANCE	SAMPLING	MICROSCOPE	IN-COMING INSPECTION
LEAD FRAME	2	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
INCOMING INSPECTION			MANUFACTURING INSTRUCTION SHEET	DIMENSION	SAMPLING	T.M.S	PROCESS DATA SHEET
	3	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
2 CRYSTAL WELDING	4	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
3 TRANSFER MOULDING	5	SUB-CONTRACTOR	SOLDER PLATING	S.P THICKNESS	SAMPLING	FLUOROSCOPY	PROCESS DATA SHEET
4 1st PRESSING		SUB-CONTRACTOR	SPECIFICATION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
5 SOLDER PLATING	6	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
6 MARKING	7	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
7 2nd PRESS				DIMENSION	SAMPLING	VERTICAL COMPARATOR	PROCESS DATA SHEET
8 FINAL INSPECTION AND TAPING	8	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	ELECTRICAL CHARACTERISTIC	100% INSPECTION	F0 CHECKING By m/c	PROCESS DATA SHEET
9 OUTGOING INSPECTION			MANUFACTURING INSTRUCTION SHEET	TAPING STRENGTH	SAMPLING	PEEL BACK TESTER	PROCESS DATA SHEET
			QUALITY STD.	ELECTRICAL CHARACTERISTIC	SAMPLING	T0&C1 CHECKER	OGI INSP.SHEET
10-1 Pre-PACKING	9	SUB-CONTRACTOR	QUALITY STD.	APPEARANCE	SAMPLING	MICROSCOPE	OGI INSP.SHEET
10-2 PACKING	10-1	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	EXPORT CUSTOMER LIST	---	---	EXPORT DOCUMENTS
EXPORT			DAILY SHIPPING LIST	FREQUENCY			
				QUANTITY			
	10-2	INA PIANT	MANUFACTURING INSTRUCTION SHEET	EXPORT CUSTOMER LIST	---	---	EXPORT DOCUMENTS
			DAILY SHIPPING LIST	FREQUENCY			
				QUANTITY			

- PROCESS QUALITY CONTROL -

CODE : MC-146

Control No : M-9803-AKE-1

2000.04.26

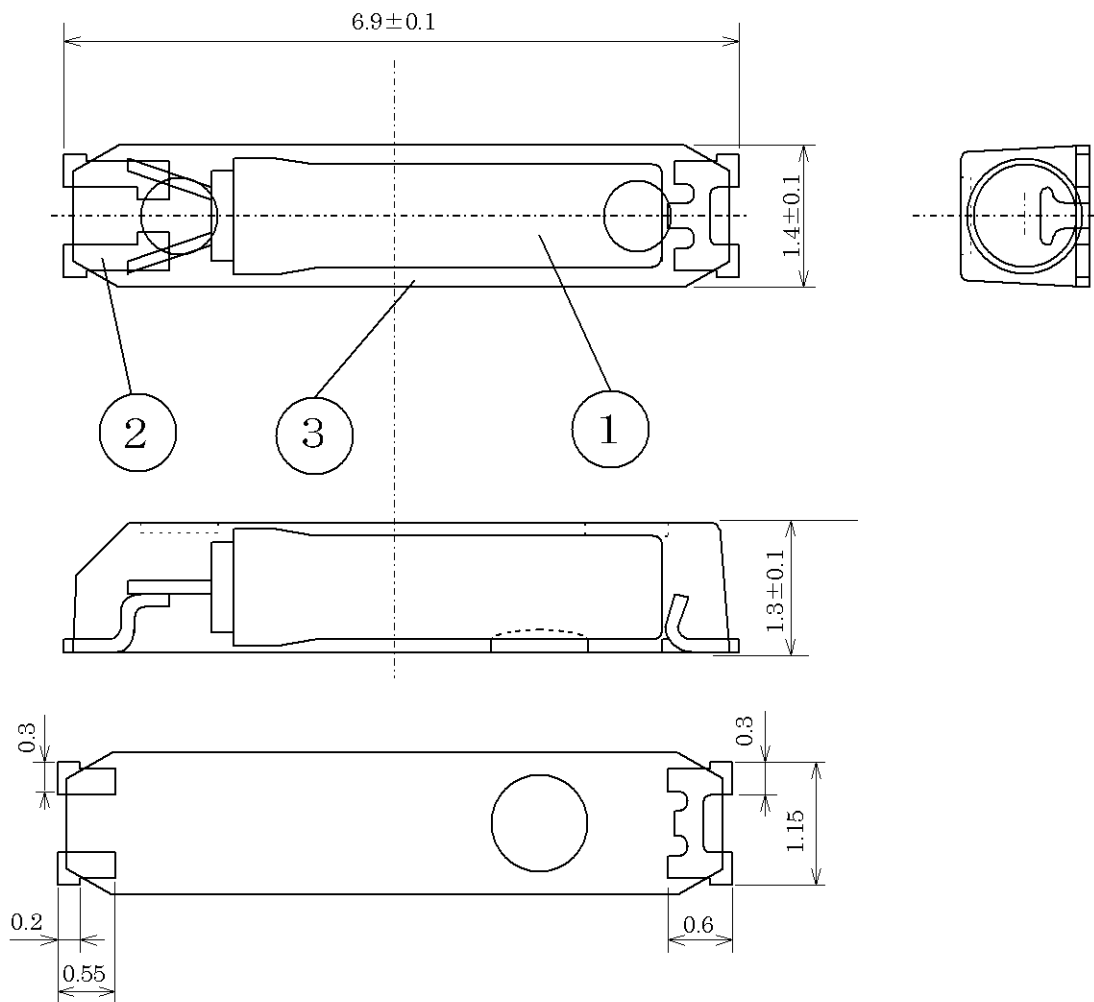
EPSON TOYOCOM CORP.
INA PLANT QZ BU

PREPARED	CHECKED	APPROVED
<i>M. Nagai</i>	<i>M. Nagai</i>	<i>M. Nagai</i>

MANUFACTURING PROCESS CHART	No	RESPONSIBLE SECTION	STANDARD AND SPECIFICATIONS	INSPECTION AND CONTROL ITEMS	INSPECTION METHOD	MEASURING INSTRUMENTS	DATA COLLECTION
The diagram shows a vertical flow of manufacturing steps. It starts with 'LEAD FRAME' and 'CRYSTAL (SiO2 COATING)' at the top. Step 1 is 'INCOMING INSPECTION' (diamond). Step 2 is 'CRYSTAL WELDING' (circle). Step 3 is 'TRANSFER MOULDING' (circle). Step 4 is '1st PRESSING' (circle). Step 5 is 'SOLDER PLATING' (circle). Step 6 is 'MARKING' (circle). Step 7 is '2nd PRESS' (circle). Step 8 is 'FINAL INSPECTION AND TAPING' (diamond). Step 9 is 'OUTGOING INSPECTION' (diamond). Step 10 is 'PACKING' (circle). The process ends with 'EXPORT' at the bottom.	1'	SUB-CONTRACTOR	PURCHASING SPECIFICATION INCOMING INSPECTION STD.	APPEARANCE DIMENSION	SAMPLING	PIUG GAUGES MICROSCOPE	IN-COMMING INSPECTION DATA SHEET
	2	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET MANUFACTURING INSTRUCTION SHEET MANUFACTURING INSTRUCTION SHEET	APPEARANCE DIMENSION STRENGTH	100% INSPECTION SAMPLING SAMPLING	MICROSCOPE T.M.S PUSH&PULL GAUGE	PROCESS DATA SHEET PROCESS DATA SHEET PROCESS DATA SHEET
	3	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	100% INSPECTION SAMPLING	MICROSCOPE	PROCESS DATA SHEET PROCESS DATA SHEET
	4	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	MICROSCOPE	PROCESS DATA SHEET
	5	SUB-CONTRACTOR SUB-CONTRACTOR	SOLDER PLATING SPECIFICATION SHEET	S.P THICKNESS APPEARANCE	SAMPLING SAMPLING	FLUOROSCOPY VISUAL INSPECTION	PROCESS DATA SHEET PROCESS DATA SHEET
	6	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET	APPEARANCE	SAMPLING	VISUAL INSPECTION	PROCESS DATA SHEET
	7	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION	APPEARANCE DIMENSION	SAMPLING SAMPLING	MICROSCOPE INSPECTION JIG	PROCESS DATA SHEET PROCESS DATA SHEET
	8	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET MANUFACTURING INSTRUCTION SHEET QUALITY STD.	ELECTRICAL CHARACTERISTIC TAPING STRENGTH ELECTRICAL CHARACTERISTIC	100% INSPECTION SAMPLING SAMPLING	F0 CHECKING By m/c STRENGTH TESTER TO&CI CHECKER	PROCESS DATA SHEET PROCESS DATA SHEET OGI INSP.SHEET
	9	SUB-CONTRACTOR	QUALITY STD.	APPEARANCE	SAMPLING	MICROSCOPE	OGI INSP.SHEET
	10	SUB-CONTRACTOR	MANUFACTURING INSTRUCTION SHEET DAILY SHIPPING LIST	EXPORT CUSTOMER LIST FREQUENCY QUANTITY			EXPORT DOCUMENTS

MC－1 4 6 Structure diagram

Unit : mm



③	Molding	Epoxy Compound (Halide free)	_____
②	Lead	42 Alloy	Sn plating
①	Crystal C-5SH	_____	_____
No.	Name of Part	Material	Remarks

RELIABILITY TEST DATA

Product Name :MC-146 (Halide free mold)

The Company evaluation condition

We evaluate environmental and mechanical characteristics by the following test condition . No. F-M-980301-05-001EH

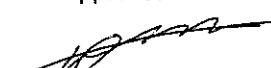
No.	ITEM	TEST CONDITIONS	VALUE *1 *2	TEST	FAIL
			$\Delta f / f$ [1×10^{-6}]	Qty [n]	Qty [n]
1	Shock	100 g dummy (ETC Standard) drop from 1 500 mm height on to the concrete 3 directions 10 times	*3 ± 5	22	0
2	Vibration	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² 10 Hz → 500 Hz → 10 Hz 15 min / cycle 6 h (2 h × 3 directions)	*3 ± 3	22	0
3	Resistance to soldering heat	For convention reflow soldering furnace (2 times) The measurement is after 24 h	± 5	22	0
4	High temperature storage	a) +125°C × 1 000 h b) +85 °C × 1 000 h	*3 a) ± 20 *3 b) ± 10	a) 22 b) 22	a) 0 b) 0
5	Low temperature storage	-55 °C × 1 000 h	*3 ± 10	22	0
6	Temperature humidity storage	+85 °C × 85 %RH × 1 000 h	*3 ± 10	22	0
7	Temperature cycle	-55 °C ⇄ +125 °C 30 min at each temp. 100 cycles	*3 ± 10	22	0
8	Shear	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	22	0
9	Pull - off	10 N press for 10 s ± 1 s Ref. IEC 60068-2-21	No peeling - off at a solder part	22	0
10	Substrate bending	Bend width reaches 3 mm and hold for 5 s ± 1 s × 1 time Ref. IEC 60068-2-21	No peeling - off at a solder part	22	0
11	Solderability	Dip termination into solder bath at +235 °C ± 10 °C for 3 s (Using Rosin Flux)	Termination must be 95 % covered with fresh solder	11	0
12	Solvent resistance	Ref. JIS C 0052 or IEC 60068-2-45	The marking shall be legible	11	0

Notes

- *1 Each test done independently.
- *2 Measuring 1 h to 24 h later leaving in room temperature after each test.
- *3 Pre conditionings Initial value shall be after 24 h at room temperature.
- Shift series resistance at after above tests should be less than ±15 % or less than ±5 kΩ.
In case Resistance to soldering heat,high temperature storage (+125 °C × 1 000 h) shift series resistance
at after above tests should be less than ±20 % or less than ±10 kΩ.

Signature

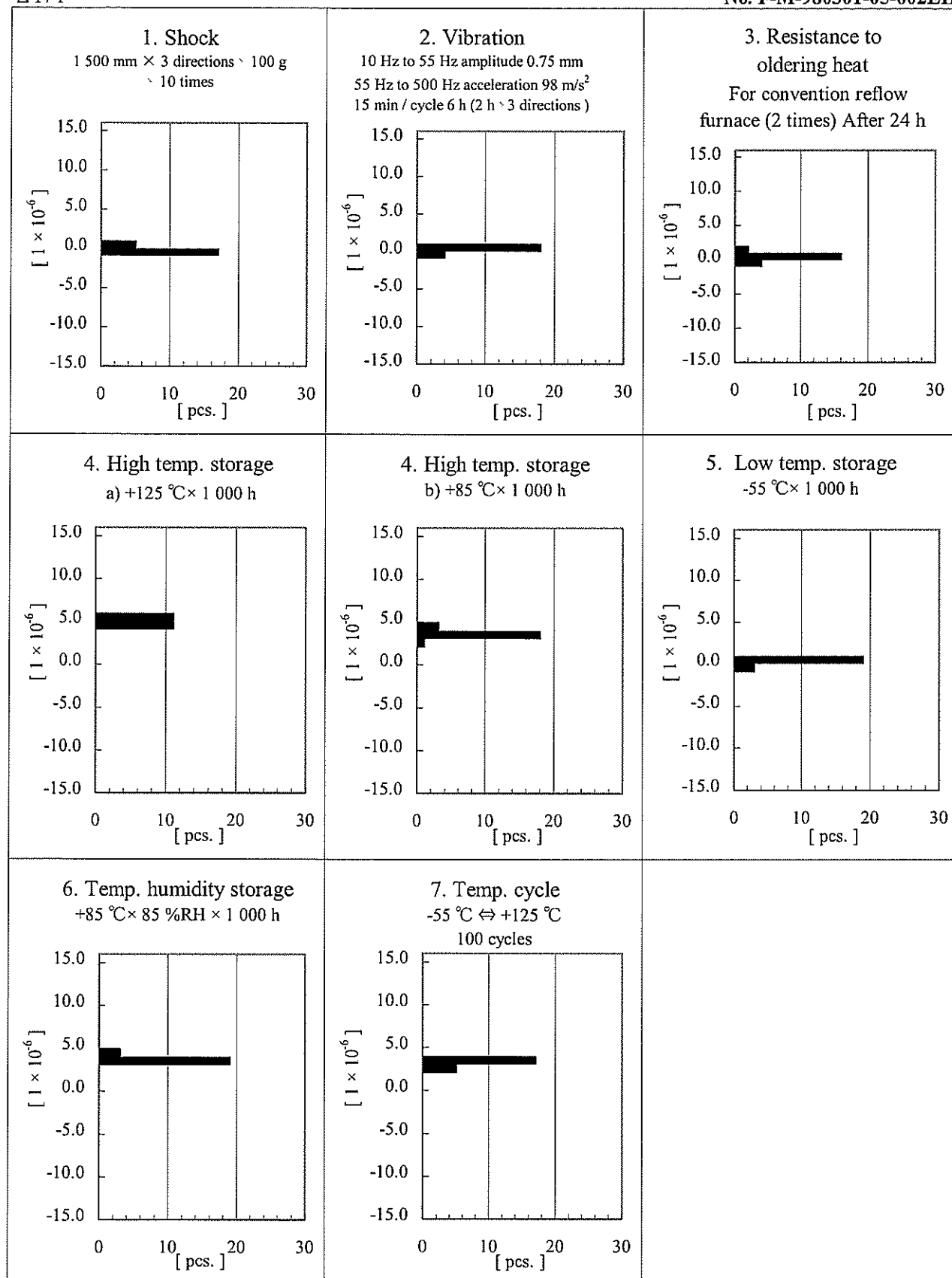
Approved


Jun Watanuki / General Manager of QZ Business unit Quality Assurance

Product Name : MC-146 (Halide free mold)

$\Delta f/f$

No. F-M-980301-05-002EH



Product Name : MC-146 (Halide free mold)

Δ CI

No. F-M-980301-05-003EH

